Texas Instruments Inc. (DUNS# 00-732-1904) Supplier Name:

Contact Info:

ti.com/support
Distribute - RoHS and IEC 62474 DB Form/Declaration Type:

05/06/2022

Details for "TLC2202ACDR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TLC2202ACDR	NIPDAU	Level-1-260C-UNLIM	TI TAIWAN A/T	D 14	3.91X8.65X1.58	199.2

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

				Homogeneous Material Level		Component Level			
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm		
Bond Wire									
Other Nonferrous Metals and Alloys	Yttrium	7440-65-5	0.000001	0.000613	6	0.000001	0		
Precious Metals	Gold	7440-57-5	0.163056	99.99816	999982	0.081854	819		
Precious Metals	Silver	7440-22-4	0.000002	0.001227	12	0.000001	0		
Sub-Total			0.163059	100	1000000	0.081856	819		
Die Attach Adhesive	Die Attach Adhesive								
Precious Metals	Silver	7440-22-4	0.768824	80	800000	0.385951	3860		
Thermoplastics	Ероху	85954-11-6	0.192206	20	200000	0.096488	965		
Sub-Total			0.96103	100	1000000	0.482439	4824		
Lead Frame									
Copper and Its Alloys	Copper	7440-50-8	78.9669	97.49	974900	39.641544	396415		
Copper and Its Alloys	Iron	7439-89-6	1.944	2.4	24000	0.975892	9759		
Copper and Its Alloys	Phosphorus	7723-14-0	0.0243	0.03	300	0.012199	122		
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.0081	0.01	100	0.004066	41		
Zinc and Its Alloys	Zinc	7440-66-6	0.0567	0.07	700	0.028464	285		
Sub-Total			81	100	1000000	40.662165	406622		
Lead Frame Plating									
Nickel and Its Alloys	Nickel	7440-02-0	8.27544	95.12	951200	4.154288	41543		
Precious Metals	Gold	7440-57-5	0.06786	0.78	7800	0.034066	341		
Precious Metals	Palladium	7440-05-3	0.3567	4.1	41000	0.179064	1791		
Sub-Total			8.7	100	1000000	4.367418	43674		
Mold Compound									
Other Inorganic Materials	Fused Silica	60676-86-0	92.608127	87.999999	880000	46.489468	464895		
Other Plastics and Rubber	Carbon Black	1333-86-4	0.31571	0.3	3000	0.158487	1585		
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.578801	0.55	5500	0.290559	2906		
Thermoplastics	Ероху	85954-11-6	11.733871	11.15	111500	5.890427	58904		
Sub-Total			105.236509	100	1000000	52.828942	528289		
Semiconductor Device									
Ceramics / Glass	Doped Silicon	7440-21-3	3.141782	100	1000000	1.577181	15772		
Sub-Total			3.141782	100	1000000	1.577181	15772		
Total			199.20238			100	1000000		

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.

See Glossary of Terms for more details.

Important Part Information

T. There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

Ti bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. Ti may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. Il and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 05/06/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials.

Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

ROHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szg088

Green: Means the content of Chlorine (CI) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.